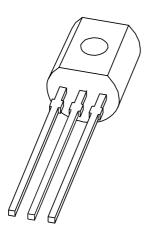
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



## MPSA42; MPSA43 NPN high-voltage transistors

Product data sheet Supersedes data of 1999 Apr 12

2004 Oct 11



## **NPN** high-voltage transistors

## MPSA42; MPSA43

#### **FEATURES**

- Low current (max. 100 mA)
- High voltage (max. 300 V).

#### **APPLICATIONS**

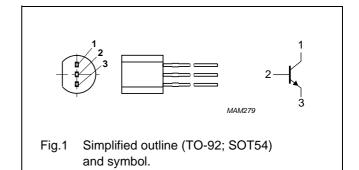
- Video
- Telephony
- Professional communication equipment.

#### **DESCRIPTION**

NPN high-voltage transistor in a TO-92; SOT54 plastic package. PNP complement: MPSA92.

#### **PINNING**

PIN	DESCRIPTION
1	collector
2	base
3	emitter



#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE	
TIPE NOWIBER	NAME	DESCRIPTION	VERSION
MPSA42	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
MPSA43			

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	MPSA42		_	300	V
	MPSA43		_	200	V
V <sub>CEO</sub>	collector-emitter voltage	open base			
	MPSA42		_	300	V
	MPSA43		_	200	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	6	V
I <sub>C</sub>	collector current (DC)		-	100	mA
I <sub>CM</sub>	peak collector current		_	200	mA
I <sub>BM</sub>	peak base current		-	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	-	500	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

## NPN high-voltage transistors

MPSA42; MPSA43

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	250	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current				
	MPSA42	V <sub>CB</sub> = 200 V; I <sub>E</sub> = 0 A	_	100	nA
	MPSA43	V <sub>CB</sub> = 160 V; I <sub>E</sub> = 0 A	_	100	nA
I <sub>EBO</sub>	emitter-base cut-off current				
	MPSA42	V <sub>EB</sub> = 6 V; I <sub>C</sub> = 0 A	_	100	nA
	MPSA43	V <sub>EB</sub> = 4 V; I <sub>C</sub> = 0 A	_	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 10 V; note 1			
		$I_C = 1 \text{ mA}$	25	_	
		I <sub>C</sub> = 10 mA	40	_	
		$I_C = 30 \text{ mA}$	40	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 20 mA; I <sub>B</sub> = 2 mA; note 1	_	500	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = 20 \text{ mA}; I_B = 2 \text{ mA}; \text{ note 1}$	_	900	mV
C <sub>c</sub>	collector capacitance	$V_{CB} = 20 \text{ V}; I_E = i_e = 0 \text{ A}; f = 1 \text{ MHz}$			
	MPSA42		_	3	pF
	MPSA43		_	4	pF
f <sub>T</sub>	transition frequency	$V_{CE} = 20 \text{ V}; I_{C} = 10 \text{ mA}; f = 100 \text{ MHz}$	50	_	MHz

#### Note

1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

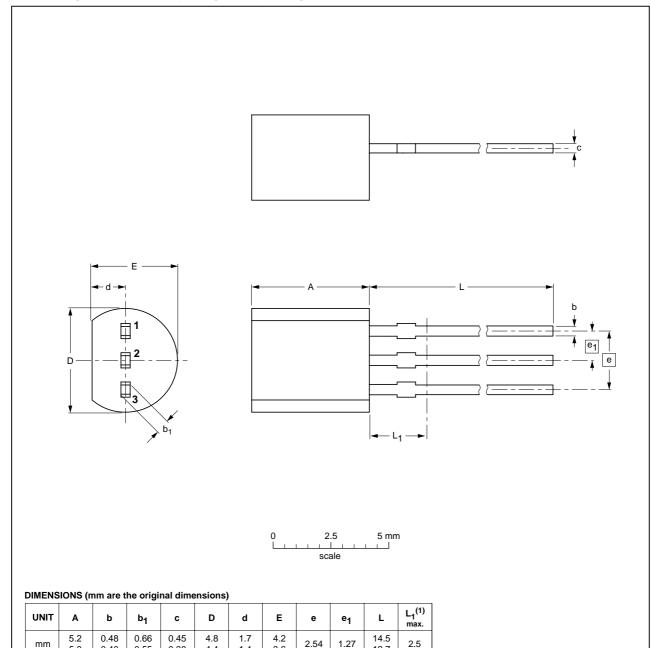
## NPN high-voltage transistors

MPSA42; MPSA43

#### **PACKAGE OUTLINE**

#### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



#### Note

0.40

0.55

0.38

4.4

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

1.4

3.6

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A			<del>-04-06-28</del> 04-11-16

12.7

## NPN high-voltage transistors

MPSA42; MPSA43

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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